

**In the Claims:**

Please cancel claims 1-8 and 14-20. The claims are as follows:

1-8. (Canceled)

9. (Currently amended) An electronic structure, comprising:

a substrate, wherein the substrate is selected from the group consisting of a ceramic chip carrier, an organic chip carrier, and a printed circuit board; and  
a semiconductor device electrically coupled to the substrate, wherein the semiconductor device is divided into a plurality of segments.

10. (Original) The electronic structure of claim 9, wherein the length of each segment of the semiconductor device is greater than or equal to 5 millimeters.

11. (Original) The electronic structure of claim 9, wherein a first segment and a second segment of the plurality of segments are congruent with respect to each other.

12. (Original) The electronic structure of claim 9, wherein a first segment and a second segment of the plurality of segments are not congruent with respect to each other.

13. (Original) The electronic structure of claim 9, wherein the plurality of segments are square segments.

14-20. (Canceled)

21. (New) The electronic structure of claim 9, wherein the substrate is symmetrically coupled to each segment of the semiconductor device.

22. (New) The electronic structure of claim 9, wherein the substrate is not symmetrically coupled to each segment of the semiconductor device.

23. (New) The electronic structure of claim 9, wherein the semiconductor device is a semiconductor chip.

24. (New) The electronic structure of claim 9, wherein the substrate comprises a coefficient of thermal expansion that is greater than a coefficient of thermal expansion of the semiconductor device.

25. (New) A method for forming an electronic structure, comprising:  
dividing a semiconductor device into a plurality of segments, and  
electrically coupling a substrate to each segment of the plurality of segments of the semiconductor device, wherein the substrate is selected from the group consisting of a ceramic chip carrier, an organic chip carrier, and a printed circuit board.

26. (New) The method of claim 25, wherein each segment of the semiconductor device is

symmetrically coupled to the substrate.

27. (New) The method of claim 25, wherein each segment of the semiconductor device is not symmetrically coupled to the substrate.

28. (New) The method of claim 25, wherein a first segment and a second segment of the plurality of segments are congruent with respect to each other.

29. (New) The method of claim 25, wherein a first segment and a second segment of the plurality of segments are not congruent with respect to each other.

30. (New) The method of claim 25, wherein the length of each segment of the semiconductor device is greater than or equal to 5 millimeters.

31. (New) The method of claim 25, wherein the plurality of segments are square segments.

32. (New) The method of claim 25, wherein the semiconductor device is a semiconductor chip.

33. (New) The method of claim 25, wherein the substrate comprises a coefficient of thermal expansion that is greater than a coefficient of thermal expansion of the semiconductor device.